



Subject: ON Semiconductor PRODUCT/PROCESS CHANGE NOTIFICATION 10060

TITLE: MC33072 DIE FABRICATION AT ALLEGRO MICROSYSTEMS

EFFECTIVE DATE: 05-FEB-00

AFFECTED CHANGE CATEGORIES

Subcontractor Fab Site

AFFECTED PRODUCT DIVISIONS

ANALOG DIV

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office.

Ref: RJJ930

SAMPLES: Contact Below
Contact your local ON Semiconductor Sales Office.

Ref: R23126@email.sps.mot.com

For any questions concerning this notification:
REFERENCE:KIMBERLY WHITE PHONE: 480-413-4431

DISCLAIMER:

ON SEMICONDUCTOR WILL CONSIDER THIS CHANGE APPROVED UNLESS SPECIFIC
CONDITIONS OF ACCEPTANCE ARE PROVIDED IN WRITING WITHIN 30 DAYS OF
RECEIPT OF THIS NOTICE. TO DO SO, CONTACT YOUR LOCAL ON
SEMICONDUCTOR SALES OFFICE.

GPCN FORMAT: CUSTOMER

DO NOT REPLY TO THIS MESSAGE.

ISSUE DATE: 28-Oct-1999
EFFECTIVE DATE: 05-Feb-2000

NOTIFICATION #:10060
ISSUING DIVISION:PHX-GPPD

DESCRIPTION AND PURPOSE

To meet our growing business needs and additional capacity requirements, the MC33072 device series is being qualified for processing at Allegro Microsystems. The Allegro wafer processing fab located at Willow Grove, PA. has been approved and previously qualified for the MC1413 and the MC34063 product families. The purpose is to provide an additional wafer capacity to supplement other existing ON Semiconductor approved manufacturing sites. The exact same masking layers are being used at the Allegro fab as is presently being used at other ON Semiconductor wafer fabs. The wafer process being used is standard linear, EPI 78 flow.

QUALIFICATION PLAN

Same as Reliability Data

RELIABILITY DATA SUMMARY

BMC to Allegro Fab Transfer

MC33072AP Reliability Qual Summary Rel ID 0082

TEST	TEST CONDITIONS	SS x Lots	TEST POINTS	TEST RESULTS		
				Lot A	Lot B	Lot C
HTOL	TA=125DegC	77 x 3 lots	168 Hrs	0/77	0/77	0/77
			504 Hrs	0/77	0/77	0/77
			1008 Hrs	0/77	0/77	0/77
HTB	175DegC	77 x 0 lots	500 Hrs Generic	Generic	Generic	
H3TRB	TA=+85DegC, RH=85%	77 x 3 lots	168 Hrs	0/77	0/77	0/77
			504 Hrs	0/77	0/77	0/77
			1008 Hrs	0/77	0/77	0/77
HAST	TA=130DegC, RH=85% 18.8 PSIG	77 x 3 lots	48 Hrs	0/77	0/77	0/77
			96 Hrs	0/77	0/77	0/77
Autoclave	121DegC/100% RH/15 PSIG	77 x 3 lots	96 Hrs	0/77	0/77	0/77
			144 Hrs	0/76	0/76	0/76
Temp Cyc	-65DegC to +150DegC;	77 x 3 lots	100 cyc	0/77	0/77	0/77
			500 cyc	0/77	0/77	0/77
			1000 cyc	0/77	0/77	0/77
Solder Heat	260DegC for 10 sec	77 x 3 lots	Endpoint	0/22	0/22	0/22

ELECTRICAL CHARACTERISTIC SUMMARY

Available upon request.

CHANGED PART IDENTIFICATION

Customers may see product starting with Date Code 0006.



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FILE FORMAT: ASCII TEXT

FONT - Courier

SIZE - 12 Point

LINE - 70 characters/line

PAGE - 55 lines/page

PAGEBREAK CHARACTER - ^L (Control L)

AFFECTED DEVICE LIST (WITHOUT SPECIALS)

FMC33072AD , FMC33072ADR2 , FMC33072D , FMC33072DR2
FMC34072D , FMC34072DR2 , MC33072AD , MC33072ADR2
MC33072AP , MC33072D , MC33072DR2 , MC33072P
MC34072AD , MC34072ADR2 , MC34072AP , MC34072D
MC34072DR2 , MC34072P , MC34072VD , MC34072VDR2
MC34072VP , SC111954DR2